



Substrate Guide for safe installation of: valid for Great Britain



Adhesive:	DLW Vinyl conductive	DLW Vinyl ESD
Dispersion Adhesive	F 57	F 57

Subfloor preparation for above mentioned floorings:

Type of subfloor	Calcium sulphate screed and Calcium sulphate flowing screed	Cement screed	Concrete and vacuum concrete
Permitted residual moisture	≤ 0,5 % (CM)	≤ 2,0 % (CM)	
There must be no seepage of moisture into the substrate to be covered.			
Preparation of the subfloor Sequence procedure	In all cases please refer to Sub-Floor Preparation Guide and Sector Chart @ www.f-ball.co.uk		
Primer Dispersion primer: Epoxy resin primer:	P121	P131	P131
Levelling compound Layer thickness: min. 2 mm	In all cases please refer to Sub-Floor Preparation Guide and Sector Chart @ www.f-ball.co.uk		

These recommendation have been primarily designed as a standard for new buildings. In individual cases, deviations are possible following prior consultation with F. Ball and Co. Ltd. In such cases and during renovation work, please consult F. Ball and Co. Ltd. under +44 (0) 1538 361 633. Technical information and instructions from the manufacturer are to be considered. The manufacturer is responsible for the usage of all resources according to its terms and conditions.



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Adhesive:

DLW Vinyl conductive

Dispersion Adhesive

Thomsit K112
In combination with Thomsit R762 Conductive Base Coat

DLW Vinyl ESD

Thomsit K112 (*) Thomsit K113
In combination with Thomsit R762 Conductive Base Coat

* Dependent of the flooring material and the maximum flooring resistant.

Subfloor preparation for above mentioned floorings:

Type of subfloor	Calcium sulphate screed and Calcium sulphate flowing screed	Cement screed	Concrete and vacuum concrete
Permitted residual moisture	≤ 0,5 % (CM)	≤ 2,0 % (CM)	
	There must be no seepage of moisture into the substrate to be covered.		
Preparation of the subfloor Sequence procedure	sand down brush vacuum off	brush vacuum off	brush vacuum off blast or mill vacuum off
Primer Dispersion primer: Epoxy resin primer:	Thomsit R766 or R777	Thomsit R766 or R777 Thomsit R755	Thomsit R755 twice primed, plus fire-dried quartz sand grain size 0,3 - 0,7 mm; at least 2 kg/m ²
Levelling compound Layer thickness: min. 2 mm	Thomsit DX, XXL, SL85	Thomsit DX, XXL, SL85	Thomsit DX, XXL, SL85

These recommendation have been primarily designed as a standard for new buildings. In individual cases, deviations are possible following prior consultation with Henkel AG & Co. KG aA. In such cases and during renovation work, please consult Henkel AG & Co. KG under +49 (0)211 - 7 97100 or webside www.Thomsit.com. Technical information and instructions from the manufacturer are to be considered. The manufacturer is responsible for the usage of all resources according to its terms and conditions.



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Adhesive:	DLW Vinyl conductive	DLW Vinyl ESD
Dispersion Adhesive	L 76	L 76

Subfloor preparation for above mentioned floorings:

Type of subfloor	Calcium sulphate screed and Calcium sulphate flowing screed	Cement screed	Concrete and vacuum concrete
Permitted residual moisture	≤ 0,5 % (CM)	≤ 2,0 % (CM)	
There must be no seepage of moisture into the substrate to be covered.			
Preparation of the subfloor Sequence procedure	Please contact www.laybond.net for guidance	Please contact www.laybond.net for guidance	Please contact www.laybond.net for guidance
Primer Dispersion primer:	Screedmaster Universal Primer	Screedmaster Universal Primer	
Epoxy resin primer:	Screedmaster Ep epoxy Primer	Screedmaster Epoxy Primer	
Levelling compound Layer thickness: min. 2 mm	Screedmaster Gypsum	Screedmaster 1or 2 Ultimate	

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Adhesive:	DLW Vinyl conductive	DLW Vinyl ESD
Dispersion Adhesive	UZIN KE 2000 SL UZIN KE 66 L	UZIN KE 2000 SL UZIN KE 66 L

Subfloor preparation for above mentioned floorings:

Type of subfloor	Calcium sulphate screed and Calcium sulphate flowing screed	Cement screed	Concrete and vacuum concrete
Permitted residual moisture	≤ 75 % rh	≤ 75 % rh	≤ 75 % rh
	There must be no seepage of moisture into the substrate to be covered.		
Preparation of the subfloor Sequence procedure	remove all materials that could effect the performance of the recommended system plane to vacuum	plane to vacuum	plane or blast or mill to vacuum
Primer Dispersion primer: Epoxy resin primer:	UZIN PE 360	UZIN PE 360 PE414 T + 0.3 / 0.7 mm grit	UZIN PE 360 PE414 T + 0.3 / 0.7 mm grit
Levelling compound Layer thickness: min. 2 mm	UZIN NC 110	NC145, NC152 NC170 NC172	NC145, NC152 NC170 NC172

These recommendation have been primarily designed as a standard for new buildings. In individual cases, deviations are possible following prior consultation with Uzin Utz AG. In such cases and during renovation work, please consult Uzin Utz AG under +49 (0) 731 -4097257 or webside www.uzin-utz.com. Technical information and instructions from the manufacturer are to be considered. The manufacturer is responsible for the usage of all resources according to its terms and conditions.